

64K x 4 Static RAM with Separate I/O

Features

- High speed
 - 12 ns
- CMOS for optimum speed/power
- Low active power
 - 860 mW
- Low standby power
 - 55 mW
- TTL-compatible inputs and outputs
- Automatic power-down when deselected
- Available in non Pb-free 28-Lead Molded SOJ package.

Functional Description

The CY7C192 is a high-performance CMOS static RAM organized as 65,536 x 4 bits with separate I/O. Easy memory expansion is provided by active LOW Chip Enable (\overline{CE}) and tri-state drivers. It has an automatic power-down feature, reducing the power consumption by 75% when deselected.

Writing to the device is accomplished when the Chip Enable (\overline{CE}) and write enable (\overline{WE}) inputs are both LOW.

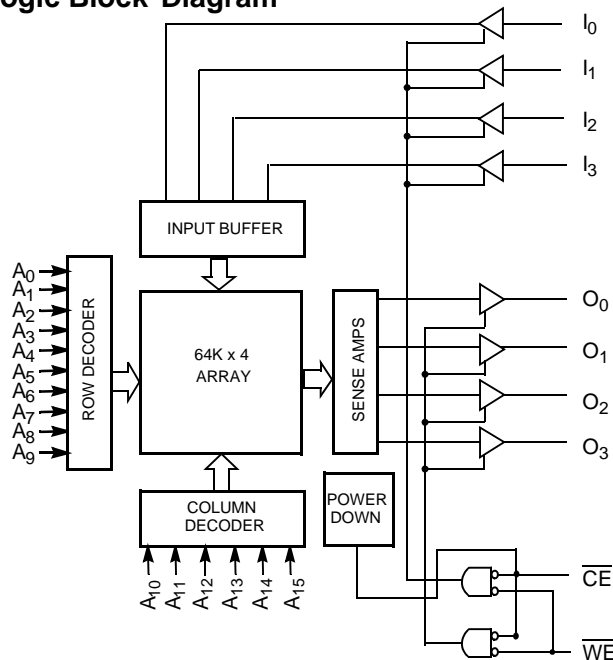
Data on the four input pins (I_0 through I_3) is written into the memory location specified on the address pins (A_0 through A_{15}).

Reading the device is accomplished by taking the Chip Enable (\overline{CE}) LOW while the Write Enable (\overline{WE}) remains HIGH. Under these conditions the contents of the memory location specified on the address pins will appear on the four data output pins.

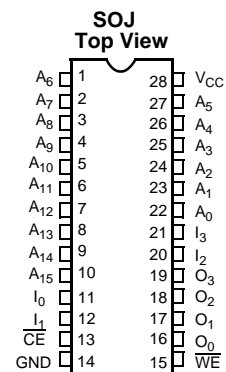
The output pins stay in high-impedance state when Write Enable (\overline{WE}) is LOW, or Chip Enable (\overline{CE}) is HIGH.

A die coat is used to insure alpha immunity.

Logic Block Diagram



Pin Configurations



Selection Guide

	-12	-15	Unit
Maximum Access Time	12	15	ns
Maximum Operating Current	155	145	mA
Maximum CMOS Standby Current	10	10	mA

Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature	-65°C to +150°C
Ambient Temperature with Power Applied.....	-55°C to +125°C
Supply Voltage to Ground Potential	-0.5V to +7.0V
DC Voltage Applied to Outputs in High Z State ^[1]	-0.5V to $V_{CC} + 0.5V$

DC Input Voltage ^[1]	-0.5V to $V_{CC} + 0.5V$
Output Current into Outputs (LOW).....	20 mA
Static Discharge Voltage.....	>900V (per MIL-STD-883, Method 3015)
Latch-Up Current.....	>200 mA

Operating Range

Range	Ambient Temperature ^[2]	V_{CC}
Commercial	0°C to +70°C	5V ± 10%

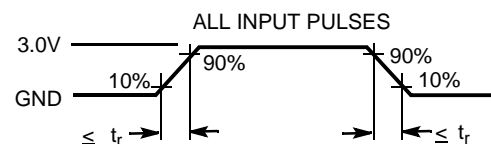
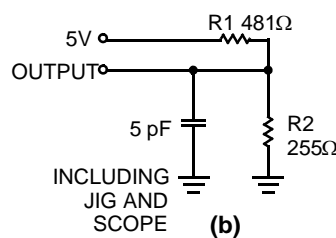
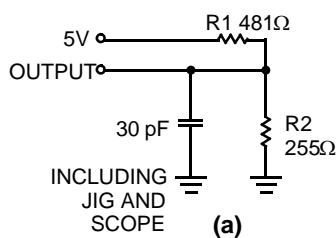
Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions	-12		-15		Unit
			Min.	Max.	Min.	Max.	
V_{OH}	Output HIGH Voltage	$V_{CC} = \text{Min.}, I_{OH} = -4.0 \text{ mA}$	2.4		2.4		V
V_{OL}	Output LOW Voltage	$V_{CC} = \text{Min.}, I_{OL} = 8.0 \text{ mA}$		0.4		0.4	V
V_{IH}	Input HIGH Voltage		2.2	$V_{CC} + 0.3V$	2.2	$V_{CC} + 0.3V$	V
V_{IL}	Input LOW Voltage ^[1]		-0.5	0.8	-0.5	0.8	V
I_{IX}	Input Leakage Current	$GND \leq V_I \leq V_{CC}$	-5	+5	-5	+5	μA
I_{OZ}	Output Leakage Current	$GND \leq V_O \leq V_{CC}$, Output Disabled	-5	+5	-5	+5	μA
I_{CC}	V_{CC} Operating Supply Current	$V_{CC} = \text{Max.}, I_{OUT} = 0 \text{ mA}, f = f_{MAX} = 1/t_{RC}$		155		145	mA
I_{SB1}	Automatic CE Power-Down Current—TTL Inputs	Max. V_{CC} , $\overline{CE} \geq V_{IH}$, $V_{IN} \geq V_{IH}$ or $V_{IN} \leq V_{IL}$, $f = f_{MAX}$		30		30	mA
I_{SB2}	Automatic CE Power-Down Current—CMOS Inputs	Max. V_{CC} , $\overline{CE} \geq V_{CC} - 0.3V$, $V_{IN} \geq V_{CC} - 0.3V$ or $V_{IN} \leq 0.3V$, $f = 0$		10		10	mA

Capacitance^[3]

Parameter	Description	Test Conditions	Max.	Unit
C_{IN}	Input Capacitance	$T_A = 25^\circ\text{C}, f = 1 \text{ MHz}, V_{CC} = 5.0V$	8	pF
C_{OUT}	Output Capacitance		10	pF

AC Test Loads and Waveforms^[4]



Equivalent to: THÉVENIN EQUIVALENT
167Ω
OUTPUT ———— 1.73V

Notes:

- Minimum voltage is equal to -2.0V for pulse durations of less than 20 ns.
- T_A is the case temperature.
- Tested initially and after any design or process changes that may affect these parameters.
- $t_r = \leq 3 \text{ ns}$ for the -12 and -15 speeds. $t_r = \leq 5 \text{ ns}$ for the -20 and slower speeds.

Switching Characteristics Over the Operating Range^[5]

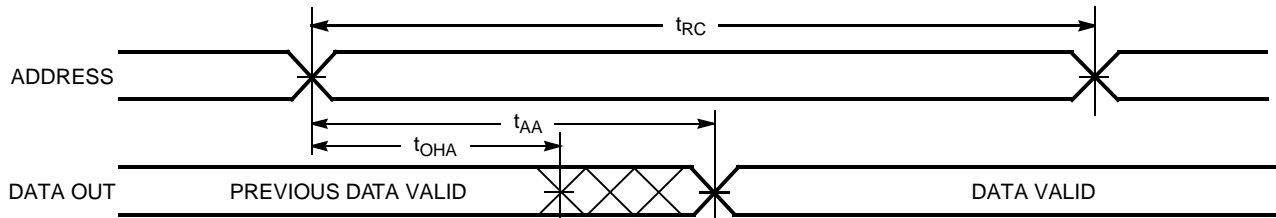
Parameter	Description	-12		-15		Unit
		Min.	Max.	Min.	Max.	
Read Cycle						
t_{RC}	Read Cycle Time	12		15		ns
t_{AA}	Address to Data Valid		12		15	ns
t_{OHA}	Output Hold from Address Change	3		3		ns
t_{ACE}	\overline{CE} LOW to Data Valid		12		15	ns
t_{LZCE}	\overline{CE} LOW to Low Z ^[6]	3		3		ns
t_{HZCE}	\overline{CE} HIGH to High Z ^[6,7]		5		7	ns
t_{PU}	\overline{CE} LOW to Power-Up	0		0		ns
t_{PD}	\overline{CE} HIGH to Power-Down		12		15	ns
Write Cycle^[8]						
t_{WC}	Write Cycle Time	12		15		ns
t_{SCE}	\overline{CE} LOW to Write End	9		10		ns
t_{AW}	Address Set-Up to Write End	9		10		ns
t_{HA}	Address Hold from Write End	0		0		ns
t_{SA}	Address Set-Up to Write Start	0		0		ns
t_{PWE}	\overline{WE} Pulse Width	8		9		ns
t_{SD}	Data Set-Up to Write End	8		9		ns
t_{HD}	Data Hold from Write End	0		0		ns
t_{LZWE}	\overline{WE} HIGH to Low Z ^[6]	3		3		ns
t_{HZWE}	\overline{WE} LOW to High Z ^[6,7]		7		7	ns

Notes:

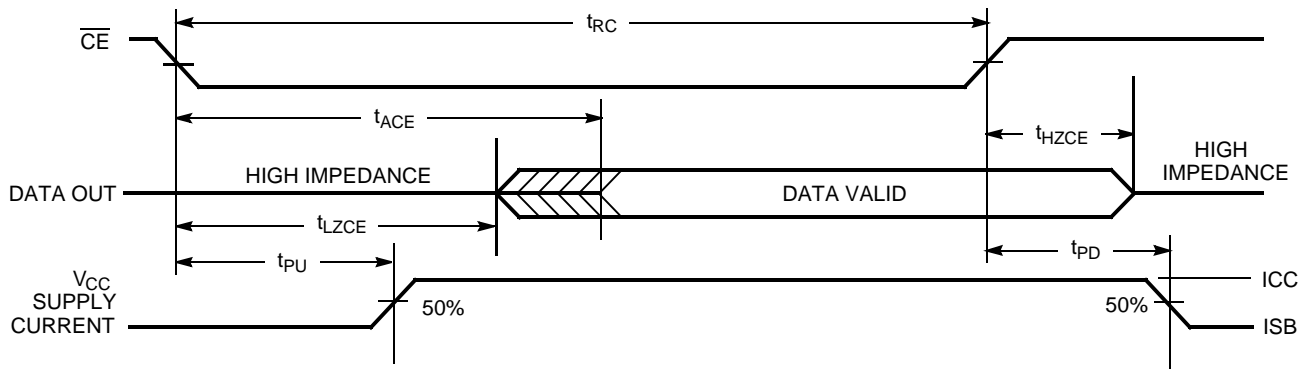
5. Test conditions assume signal transition time of 3 ns or less for -12 and -15 speeds, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified I_{OL}/I_{OH} and 30-pF load capacitance.
6. At any given temperature and voltage condition, t_{HZCE} is less than t_{LZCE} , t_{HZWE} is less than t_{LZWE} for any given device. These parameters are guaranteed by design and not 100% tested.
7. t_{HZCE} and t_{HZWE} are specified with $C_L = 5$ pF as in part (b) of AC Test Loads. Transition is measured ± 500 mV from steady-state voltage.
8. The internal write time of the memory is defined by the overlap of \overline{CE} LOW and \overline{WE} LOW. Both signals must be LOW to initiate a write and either signal can terminate a write by going HIGH. The data input set-up and hold timing should be referenced to the rising edge of the signal that terminates the write.

Switching Waveforms

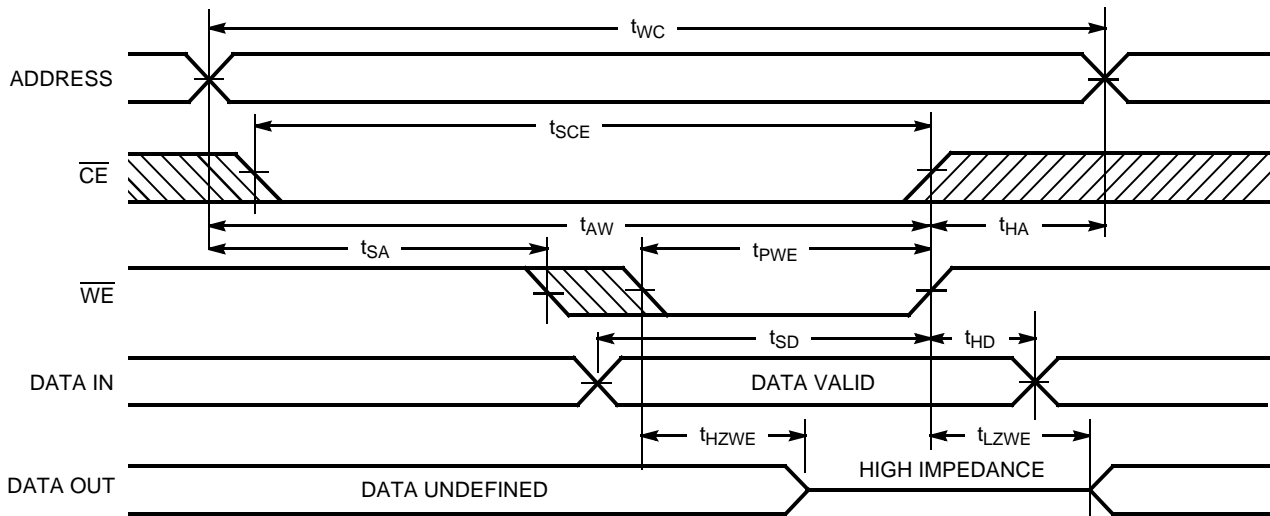
Read Cycle No. 1^[9, 10]



Read Cycle No. 2^[9, 11]



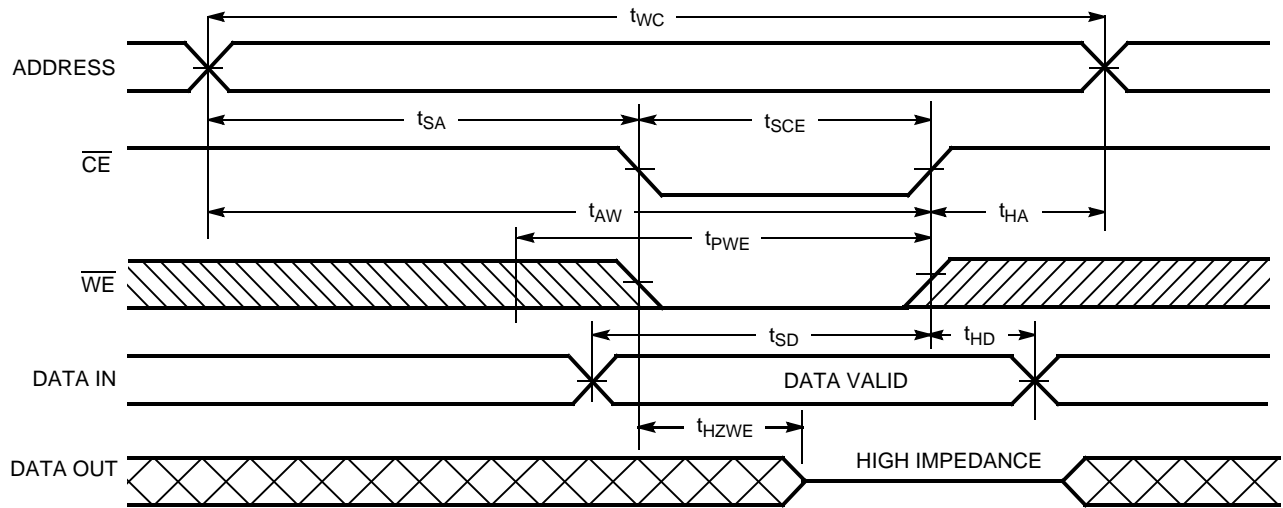
Write Cycle No. 1 (WE Controlled)^[8]



Notes:

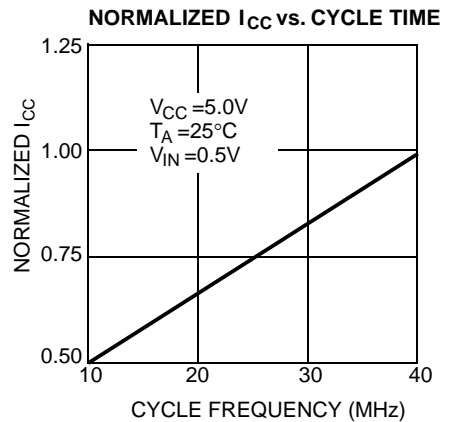
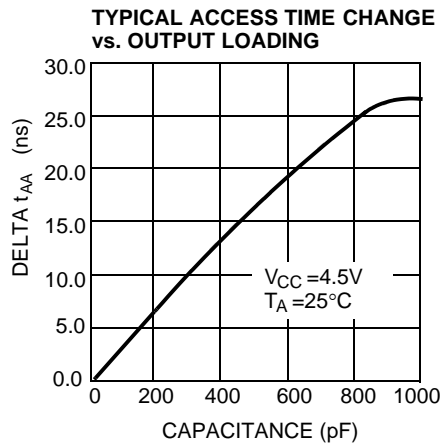
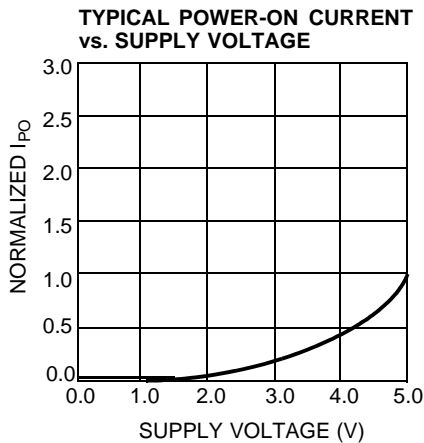
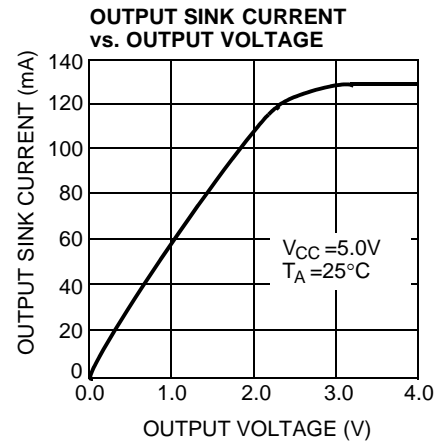
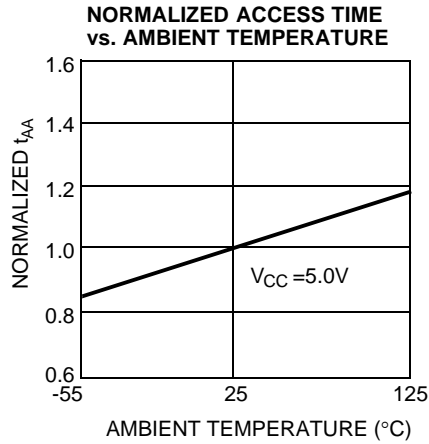
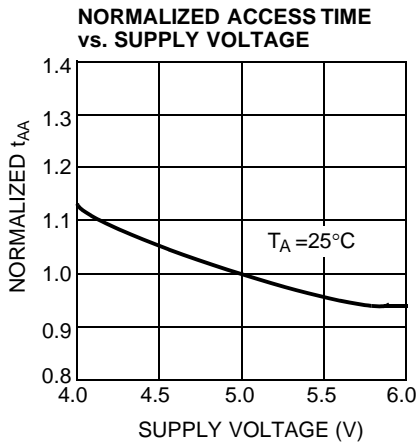
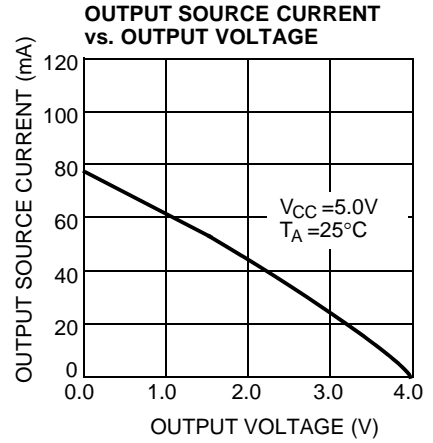
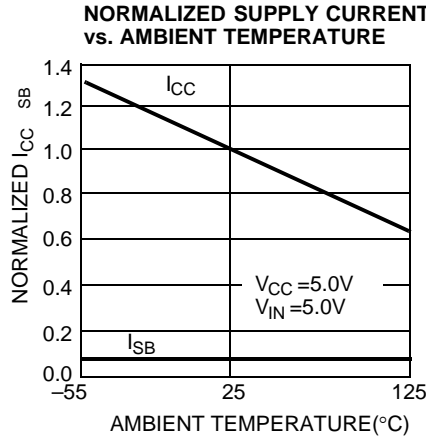
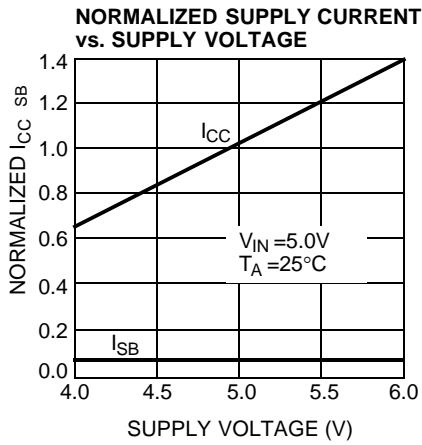
- 9. WE is HIGH for read cycle.
- 10. Device is continuously selected, $\overline{CE} = V_{IL}$.
- 11. Address valid prior to or coincident with CE transition LOW.

Switching Waveforms (continued)
Write Cycle No. 2 (\overline{CE} Controlled)^[8, 12]



Note:
 12. If \overline{CE} goes HIGH simultaneously with \overline{WE} HIGH, the output remains in a high-impedance state.

Typical DC and AC Characteristics



Ordering Information

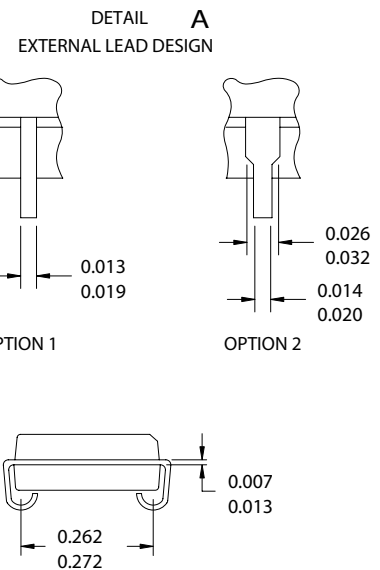
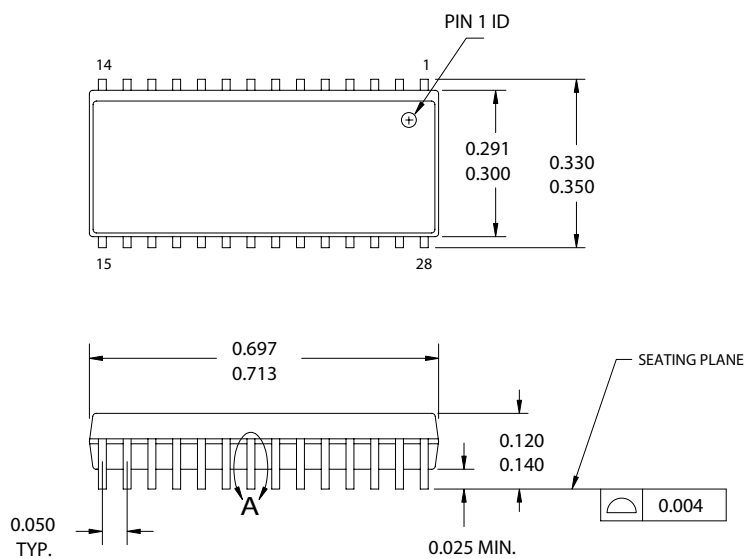
Speed (ns)	Ordering Code	Package Diagram	Package Type	Operating Range
12	CY7C192-12VC	51-85031	28-Lead Molded SOJ	Commercial
15	CY7C192-15VC			

Package Diagram

28-Lead (300-Mil) Molded SOJ (51-85031)

NOTE:

1. JEDEC STD REF MO088
2. BODY LENGTH DIMENSION DOES NOT INCLUDE MOLD PROTRUSION/END FLASH
MOLD PROTRUSION/END FLASH SHALL NOT EXCEED 0.006 in (0.152 mm) PER SIDE
3. DIMENSIONS IN INCHES
MIN.
MAX.



51-85031-°C

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Document History Page

Document Title: CY7C192 64K x 4 Static RAM with Separate I/O				
Document Number: 38-05047				
REV.	ECN NO.	Issue Date	Orig. of Change	Description of Change
**	107149	09/10/01	SZV	Change Spec number from: 38-00076 to 38-05047
*A	359716	See ECN	AJU	Changed Static Discharge Voltage limit in the Maximum Ratings section (page 2) from 2001V to 900V Removed references to CY7C191
*B	419549	See ECN	AJU	Added Pb-free parts to the Ordering Information table and replaced the Package Name column with Package Diagram
*C	492500	See ECN	NXR	Removed 20 ns and 25 ns speed bins Changed the Low active power from 220 mW to 55 mW Changed the description of I_{IX} from Input Load Current to Input Leakage Current in DC Electrical Characteristics table Removed I_{OS} parameter from DC Electrical Characteristics table Removed 28-Lead (300-Mil) PDIP package from product offering Updated Ordering Information table